Würth Elektronik eiSos GmbH & Co. KG
EMC & Inductive Solutions
Max-Eyth-Straße 1 · 74638 Waldenburg · Germany
Tel. +49 (0) 79 42 945-0 · Fax +49 (0) 79 42 945-400
eiSos@we-online.de · www.we-online.de

Product / Process Change Notification (PCN)

☐ Major change
☒ Minor change

PCN #:	PCN_WL-SMCD-20200717
Affected Series:	150060xx55040
PCN Date:	June 19, 2020
Effective Date:	July 17, 2020

Change Category:

☐ Equipment / Location
☐ General Data
☐ Material
☐ Process
☒ Product Design
☐ Shipping / Packaging
☒ Supplier
☐ Software

Contact:	Product Management
Phone:	+49 (0) 7942 - 945 5001
Fax:	+49 (0) 7942 - 945 5179
E-Mail:	pcn.eisos@we-online.com

Data Sheet Change:

☐ Yes ☒ No

Attachment:

☐ Yes ☐ No

DESCRIPTION AND PURPOSE OF CHANGE:

Due to an improvement of the production capability, Würth Elektronik will add an additional sub-supplier for the substrate.

There will be no change in form, fit, function, quality or reliability of the product.

Products after the product change with the effective date of July 17, 2020 are available with the Date code 2020-07-01.

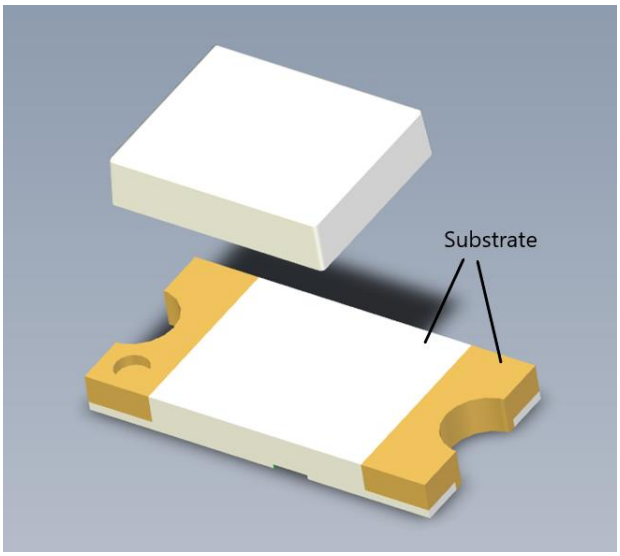

Image: Substrate of the Chip LED

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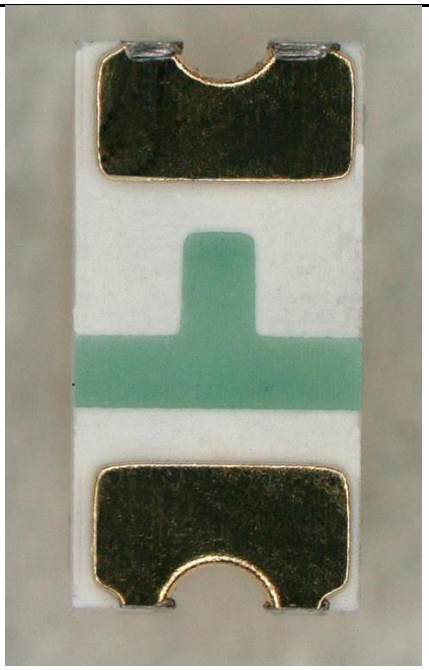
DETAIL OF CHANGE:

The color of substrates and the contact's form are slightly different. These changes do not impact on the function of the component.

First source	Second source
	
	

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WÜRTH ELEKTRONIK

RELIABILITY / QUALIFICATION SUMMARY:

Product approval is according to the specification and is released by the Product Management Department.

No.	Test	Qty	Reference	Test conditions
1	Reflow test	30	Internal Reflow Profile according to J-STD-020C	Unsoldered WE Reflow Profile: (at least 3 times must be passed) Peak: TP +5°C Conditions: Preheat: 150-200°C (max 120s) Liquidus temperature: 217°C (max 60s) Peak Temperature: 250°C (10s +/-2s)
2	Life-span in high temperature	30	Internal Spec.	Dehumidification in 125 °C for 2 hours 30 mins @ 25°C Measurement: 1,2,3,4,5 On board for 1 time Reflow Test conditions: Forward current: 30mA @ 125°C in 96h
3	Thermal Shock	30	MIL-STD-202 Method 107	Temperature: -40°C/+125°C or individual specified operating temperature Dwell time: 30 minutes. Cycles: 40 Transfer time: max. 20s
4	ESD Characterization	30	AEC - Q101-001 Rev-A.	2000V for AlInGaP 1000V for InGaN forward pulse: 3 times reversed pulse: 3 times pulse width: 1 second
5	Vibration	30	MIL-STD-202 Method 204	20g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 100mm x 160mm x 1,5mm PCB-Board. Test from 25-2000 Hz.